

Sub B¹⁹

- | Station | Time | Lat | Long | Alt | Temp | Wind | Dir | Speed | Pressure | Humidity | Clouds | Visibility | Remarks |
|---------|------|-----------|------------|-----|------|------|-----|-------|----------|----------|--------|------------|---------|
| 1 | 0000 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 2 | 0100 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 3 | 0200 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 4 | 0300 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 5 | 0400 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 6 | 0500 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 7 | 0600 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 8 | 0700 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 9 | 0800 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 10 | 0900 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 11 | 1000 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 12 | 1100 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 13 | 1200 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 14 | 1300 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 15 | 1400 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 16 | 1500 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 17 | 1600 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 18 | 1700 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 19 | 1800 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 20 | 1900 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 21 | 2000 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 22 | 2100 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 23 | 2200 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |
| 24 | 2300 | 34° 15' N | 121° 05' E | 10 | 10.0 | 10 | 000 | 0.0 | 1013.2 | 95 | 000 | 10 | Clear |

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6. The method of claim 1, wherein said bonding wires includes gold.

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wherein a second etching of said two stages of etching comprising separating said die pads and bonding pads by etching from a second side of said leadframe.

8. The method of claim 7, furthering comprising separating each individual package by cutting said leadframe and compound formed by said molding.

9. A HSQFN (High Stand-off Quad Flat Non-leaded) package, comprising:

a leadframe having a die pad and bonding pads, wherein said die pad is designed to carry a die adhesived thereon by adhesive material, wherein said die pad and bonding pads are separated;

a plurality of bonding wires connected between said bonding pads and said die for electrical communication; and

molding compound encompasses said die, said bonding wires and a first surface of said lead frame, leaving the terminal of said bonding pads and the lower surface of said die pad exposed out of said compound for providing excellent thermal dissipation from said packages, wherein said exposed bonding pads is used for communication terminal for said package.

11. The HSQFN package of claim 10, wherein said adhesive material includes epoxy.

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